

# **DSA2311**

# Crystal-less<sup>TM</sup> Configurable Two-Output Clock Generator for Automotive

#### **Features**

- Automotive AEC-Q100 Qualified
- · Two Simultaneous CMOS Outputs
- Output 1 Range: 2.3 MHz to 170 MHz
- Output 2 Range: 2.3 MHz to 170 MHz
- Low RMS Phase Jitter: <1 ps (typ.)</li>
- High Stability: ±20 ppm, ±25 ppm, ±50 ppm
- · Wide Temperature Range:
  - Automotive Grade 1: -40°C to +125°C
  - Automotive Grade 2: -40°C to +105°C
  - Automotive Grade 3: -40°C to +85°C
- High Supply Noise Rejection: -50 dBc
- · High Shock and Vibration Immunity
  - Qualified to MIL-STD-883
- · High Reliability
  - 20x higher MTBF than crystal-based clock generator designs
- Supply Range of 2.25 to 3.63V
- · Lead-Free and RoHS Compliant

# **Applications**

- Automotive Infotainment
- Automotive ADAS
- · Automotive Camera Module
- · Automotive LIDAR and RADAR

#### **Benefits**

 Replace High Temperature Crystals and Quartz Oscillators

#### **General Description**

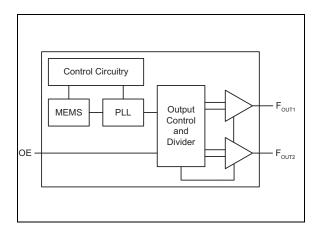
The DSA2311 is a crystal-less™ clock generator that is factory-configurable to simultaneously output two separate frequencies from 2.3 MHz to 170 MHz. The clock generator uses proven silicon MEMS technology to provide low jitter and high frequency stability across a wide range of supply voltages and temperatures. By eliminating the external quartz crystal, crystal-less clock generators significantly enhance reliability and accelerate product development, while meeting stringent clock performance criteria for a variety of consumer electronics, communications, and storage applications.

DSA2311 has an Output Enable/Disable feature that allows it to disable the outputs when OE is low. The device is available in a space-saving 6-pin 2.5 mm x 2.0 mm crystal-less VDFN package that uses only a single external bypass capacitor.

The two output frequencies can be customized by using Clockworks:

http://clockworks.microchip.com/timing

#### **Block Diagram**



#### 1.0 ELECTRICAL CHARACTERISTICS

## **Absolute Maximum Ratings †**

Input Voltage, V <sub>IN</sub>	–0.3V to V <sub>DD</sub> +0.3V
Supply Voltage	
ESD Protection (HBM)	4 kV
ESD Protection (CDM)	1.5 kV

**<sup>†</sup> Notice:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: ELECTRICAL CHARACTERISTICS

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Supply Voltage (Note 1)	V <sub>DD</sub>	2.25	_	3.6	٧	_
Supply Current (Note 2)	I <sub>DD</sub>	_	21	23	mA	EN pin low. All outputs disabled.
		_	_	±20		Includes frequency variations
Frequency Stability (Note 3)	Δf	_	_	±50	ppm	due to initial tolerance, temperature, and power supply voltage.
Aging	Δf	_	_	±5	ppm	One year at +25°C
Start-up Time (Note 4)	t <sub>SU</sub>	_	_	5	ms	T = +25°C
Input Logic Levels	$V_{IH}$	0.75 x V <sub>DD</sub>	_		<b>V</b>	Input logic high
iliput Logic Levels	$V_{IL}$	_	_	0.25 x V <sub>DD</sub>	V	Input logic low
Output Disable Time	t <sub>DA</sub>	_	_	5	ns	_
Output Enable Time	t <sub>EN</sub>	_	_	20	ns	_
Pull-Up Resistor (Note 2)	_	_	40	_	kΩ	Pull-up exists on all digital IO
Output Logic Levels	$V_{OH}$	0.9 x V <sub>DD</sub>	_	_	V	Output logic high, I = ±6 mA
Output Logic Levels	$V_{OL}$	_	_	0.1 x V <sub>DD</sub>	V	Output logic low, I = ±6 mA
Output Transition Rise Time	t <sub>R</sub>	_	1.1	2.0	no	20% to 80%; C <sub>L</sub> = 15 pF
Output Transition Rise Time	t <sub>F</sub>	_	1.4	2.0	ns	20% to 80%; C <sub>L</sub> = 15 pF
		2.3	_	170		Grade 3 temp. range
Frequency	$f_0$	3.3	_	100	MHz	Grade 1 temp. range
		3.3	_	170		Grade 2 temp. range
Output Duty Cycle	SYM	45	_	55	%	_
Period Jitter (Note 5)	$J_{PER}$	_	3		ps <sub>RMS</sub>	F <sub>O1</sub> = F <sub>O2</sub> = 25 MHz
		_	0.3	_		200 kHz to 20 MHz @ 25 MHz
Integrated Phase Noise	$J_{CC}$	_	0.38		ps <sub>RMS</sub>	100 kHz to 20 MHz @ 25 MHz
		_	1.7	2		12 kHz to 20 MHz @ 25 MHz

Note 1: Pin 4  $V_{DD}$  should be filtered with a 0.01  $\mu F$  capacitor.

- 2: Output is enabled if Enable pad is floated or not connected. Operating current = disabled current +  $\Delta I_{DD}$  from  $F_{OUT1}$  +  $\Delta I_{DD}$  from  $F_{OUT2}$ . See graph for more information.
- 3: For other ppm stabilities, please contact the factory.
- 4: t<sub>SU</sub> is time to 100 ppm stable output frequency after V<sub>DD</sub> is applied and outputs are enabled.
- 5: Period jitter includes crosstalk from adjacent output.

# **TEMPERATURE SPECIFICATIONS (Note 1)**

	1	1	1				
Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions	
Temperature Ranges							
	T <sub>A</sub>	-40	_	+85	°C	Ordering Option I	
Operating Temperature Range (T)	T <sub>A</sub>	-40	_	+105	°C	Ordering Option L	
	T <sub>A</sub>	-40	_	+125	°C	Ordering Option A	
Junction Operating Temperature	TJ	_	_	+150	°C	_	
Storage Temperature Range	T <sub>A</sub>	-40		+150	°C	_	
Soldering Temperature Range	T <sub>S</sub>	_		+260	°C	40 sec. max.	

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T<sub>A</sub>, T<sub>J</sub>, θ<sub>JA</sub>). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +150°C rating. Sustained junction temperatures above +150°C can impact the device reliability.

# 2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description	
1	ENABLE	Output Enable for both CLK0 and CLK1.	
2	N/C	Do not connect.	
3	GROUND	Ground.	
4	CLK0	Clock Output 0 (CMOS).	
5	CLK1	Clock Output 1 (CMOS).	
6	VDD	Supply Voltage.	

# 3.0 OUTPUT WAVEFORM

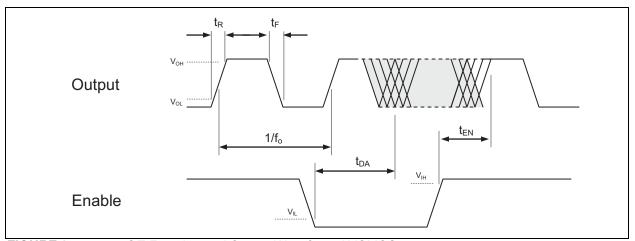
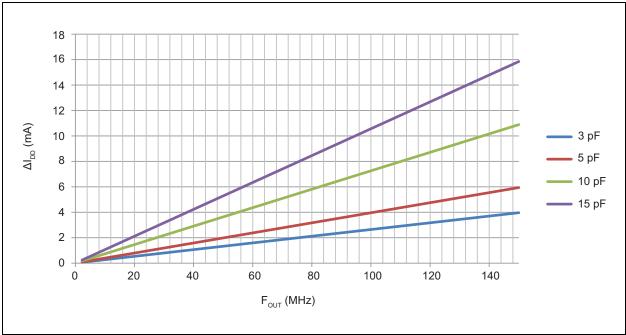


FIGURE 3-1: OE Function and Output Waveform: LVCMOS.

# 4.0 CURRENT CONSUMPTION

Total Current = Disabled Current +  $\Delta I_{DD} F_{OUT1} + \Delta I_{DD} F_{OUT2}$ 



**FIGURE 4-1:**  $\Delta I_{DD}$  / Output vs. Frequency and Load @ 3.3V  $V_{DD}$ .

# 5.0 SOLDER REFLOW PROFILE

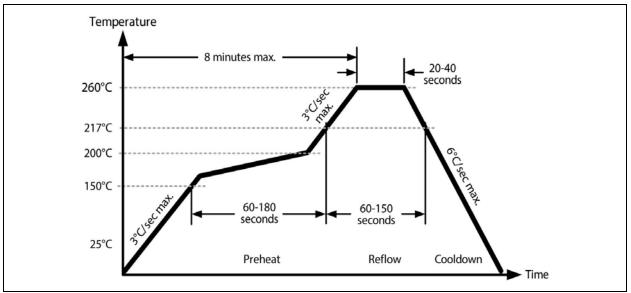


FIGURE 5-1: Solder Reflow Profile.

TABLE 5-1: SOLDER REFLOW

MSL 1 @ 260°C Refer to JSTD-020C				
Ramp-Up Rate (200°C to Peak Temp.)	3°C/sec. max.			
Preheat Time 150°C to 200°C	60 to 180 sec.			
Time Maintained above 217°C	60 to 150 sec.			
Peak Temperature	255°C to 260°C			
Time within 5°C of Actual Peak	20 to 40 sec.			
Ramp-Down Rate	6°C/sec. max.			
Time 25°C to Peak Temperature	8 minutes max.			

#### 6.0 PACKAGING INFORMATION

# 6.1 Package Marking Information

6-Lead VDFN\*

XXXXXXX DCPYYWW 0SSS Example

DSA2311 DCP1121 0603

**Legend:** XX...X Product code, customer-specific information, or frequency in MHz without printed decimal point

Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code

(e3) Pb-free JEDEC<sup>®</sup> designator for Matte Tin (Sn)

This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

•, ▲, ▼ Pin one index is identified by a dot, delta up, or delta down (triangle mark).

**Note**: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.

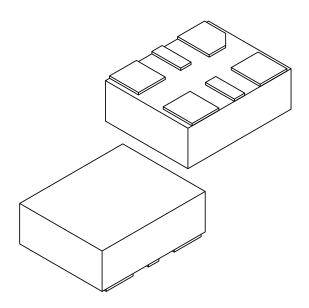
Underbar (\_) and/or Overbar (¯) symbol may not be to scale.

# 6-Lead VDFN 2.5 mm x 2.0 mm Package Outline and Recommended Land Pattern

# 6-Lead Very Thin Dual Flatpack No-Leads (J7A) - 2.5x2.0 mm Body [VDFN] For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging Note: D Ν (DATUM A) (DATUM B) E NOTE 1 0.05 C 2X 0.05 C TOP VIEW // 0.10 C SEATING PLANE 6X 0.08 C SIDE VIEW L2 5X L1 4X b1 0.10(M) C A B 0.05(M) C ⊢e-**BOTTOM VIEW** Microchip Technology Drawing C04-1005A Sheet 1 of 2

# 6-Lead Very Thin Dual Flatpack No-Leads (J7A) - 2.5x2.0 mm Body [VDFN]

For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units			MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX			
Number of Terminals	Ν	6					
Pitch	е	0.825 BSC					
Overall Height	Α	0.80	0.85	0.90			
Standoff	A1	0.00 0.02 0.05					
Overall Length	D	2.50 BSC					
Overall Width	Е	2.00 BSC					
Terminal Width	b1	0.60	0.65	0.70			
Terminal Width	b2	0.20	0.25	0.30			
Terminal Length	L1	0.60 0.70 0.80					
Terminal Length	L2	0.665 0.765 0.865					

#### Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M  $\,$

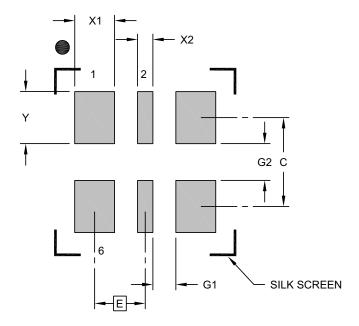
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1005A Sheet 2 of 2

### 6-Lead Very Thin Dual Flatpack No-Leads (J7A) - 2.5x2.0 mm Body [VDFN]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



### RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension Limits		MIN	NOM	MAX
Contact Pitch	Е	E 0.825 BSC		
Contact Pad Width (X4)	X1			0.65
Contact Pad Width (X2)	X2	0.2		
Contact Pad Length (X6)	Υ			0.85
Contact Pad Spacing	С		1.45	
Space Between Contacts (X4)	G1	0.38		
Space Between Contacts (X3)	G2	0.60		

#### Notes:

- Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- 2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-3005A

# **DSA2311**

NOTES:

# APPENDIX A: REVISION HISTORY

# Revision A (March 2018)

• Initial release of DSA2311 as Microchip data sheet DS20005893A.

# **DSA2311**

NOTES:

#### PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO. X X X X RXXXX X

Device Package Temperature Stability Frequency Packing Range Option

**Device:** DSA2311: Crystal-less Configurable Two-Output Clock Generator for Automotive

-40°C to +85°C (Grade 3)

Package: K = 6-LEAD 2.5 mm x 2.0 mm VDFN

Stability: 1 = ±50 ppm 2 = ±25 ppm

 $3 = \pm 20 \text{ ppm}$ 

Frequency: Rxxxx = Custom Frequency Code

## **Output Clock Frequencies**

Output frequencies are factory-configured to individual customer and product requirements, subject to output control and divider limitations. Contact sales with your custom frequency needs.

http://clockworks.microchip.com/timing/

Frequency Code	F <sub>OUT1</sub> (MHz)	F <sub>OUT2</sub> (MHz)
R0001	127	127
R0002	25	125

#### **Examples:**

a) DSA2311KL1-Rxxxx Crystal-less Configurable Two-Output Clock Generator, 6-LD VDFN, Grade 2 Temp. Range, ±50 ppm Stability, Custom Frequency (F<sub>OUT1</sub>

and F<sub>OUT2</sub>), Tube

b) DSA2311KI3-Rxxxx Crystal-less Configurable Two-Output Clock Generator, 6-LD VDFN, Grade 3 Temp. Range, ±20 ppm Stability, Custom Frequency (F<sub>OUT1</sub>

and F<sub>OUT2</sub>), Tube

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

	S	Δ	2	3	1	1
┙	v			·		

NOTES:

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